

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4423603

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ANDREW HUSKA	01/27/2017
CODY PETERSON	01/26/2017
CLINTON ADAMS	01/26/2017
SEAN KUPCOW	01/26/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ROHINNI, LLC
<b>Street Address:</b>	2139 N. MAIN STREET
<b>City:</b>	COEUR D' ALENE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83814
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15600611
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	509-324-9256
<b>Email:</b>	michelinac@leehayes.com
<b>Correspondent Name:</b>	LEE & HAYES PLLC
<b>Address Line 1:</b>	601 W RIVERSIDE AVENUE
<b>Address Line 2:</b>	SUITE 1400
<b>Address Line 4:</b>	SPOKANE, WASHINGTON 99201
<b>ATTORNEY DOCKET NUMBER:</b>	R088-0018USC5
<b>NAME OF SUBMITTER:</b>	MICHELINA SERRES
<b>SIGNATURE:</b>	/Michelina Serres/
<b>DATE SIGNED:</b>	05/19/2017
<b>Total Attachments: 2</b>	
source=1NO0760#page1.tif	
source=1NO0760#page2.tif	

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial Number .....  
Filing Date .....  
Inventorship ..... Huska et al.  
Applicant ..... Rohinni, LLC  
Attorney's Docket No. .... R088-0018USC4  
Title: Apparatus and Method for Direct Transfer of Semiconductor Devices via Stacking

**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):

Andrew Huska  
Liberty Lake, WA

Cody Peterson  
Hayden, ID

Clinton Adams  
Coeur d' Alene, ID

Sean Kupcow  
Greenacres, WA

Assignee:

Rohinni, LLC  
2139 N. Main Street  
Coeur d' Alene, ID, 83814

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled "Apparatus and Method for Direct Transfer of Semiconductor Devices via Stacking" for which:



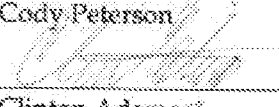
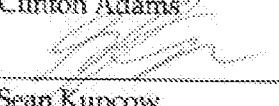
a non-provisional application for United States Letters Patent was:

filed on \_\_\_\_\_ and was given U.S. Serial No. \_\_\_\_\_ ; or filed

concurrently herewith. Assignors hereby authorize and request ASSIGNEE's legal representatives, of Lee & Hayes, PLLC, 601 W Riverside Ave, Suite 1400, Spokane, Washington 99201, who are associated with customer number 29150, to insert in the caption above the serial number and filing date of the patent application when known.

WHEREAS, Rohinni, LLC (hereinafter referred to as ASSIGNEE), a corporation of the State of Idaho having a place of business at 2139 N. Main Street, Coeur d' Alene, Idaho 83814, desires to acquire the entire right, title and interest in and to the invention and in and to any letters patent that may be granted in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE, the entire right, title and interest in and to said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent.

<u>1/27/17</u> Date	<u></u> Andrew Huska
<u>01/26/17</u> Date	<u></u> Cody Peterson
<u>1/26/17</u> Date	<u></u> Clinton Adams
<u>1/26/2017</u> Date	<u></u> Sean Kupcow